

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Chih-Tien Chang	01/04/2010
Ju-Ming Chou	01/04/2010
RECEIVING PARTY DATA	
Name:	MStar Semiconductor, Inc.
Street Address:	4F-1, No. 26, Tai-Yuan Street, ChuPei
City:	Hsinchu Hsien
State/Country:	TAIWAN
Postal Code:	302
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12692035
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NAME OF SUBMITTER:	Lynne Mahan
Total Attachments: 2 source=L56697#page1.tif source=L56697#page2.tif	

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial Number..... 12/692,035
Filing Date..... JANUARY 22, 2010
Inventorship.....
Applicant..... MStar Semiconductor, Inc.
Attorney's Docket No. M077-0006US
Client Docket No. MST0353-US
Title:

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):
1 CHIH-TIEN CHANG
2 Ju-Ming Chou

Assignee:
MStar Semiconductor, Inc.
4F-1, No. 26, Tai-Yuan Street
Chupei, Hsinchu Hsien, Taiwan 302
Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled

" Current Calibration Method and Associated Circuit "

for which:

a provisional application for United States Letters Patent was filed on _____ and was given U.S. Serial No. _____ and/or

a non-provisional application for United States Letters Patent was: filed on 01/22/2010 and was given U.S. Serial No. 12/692,035 or filed

concurrently herewith. Assignors hereby authorize and request ASSIGNEE's legal representatives, of Lee & Hayes, PLLC, 601 W Riverside Ave, Suite 1400, Spokane, Washington 99201, who are associated with customer number 29150, to insert in the caption above the serial number and filing date of the patent application when known.

WHEREAS, MStar Semiconductor, Inc. (hereinafter referred to as ASSIGNEE), a corporation of Taiwan, Republic of China having a place of business at 4F-1, No. 26, Tai-Yuan Street, Chupei, Hsinchu Hsien, Taiwan 302, Republic of China, is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE, the entire right, title and interest in and to said invention, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention,

application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

Full Name of 1st Inventor: CHIH-TIEN CHANG	
Inventor's Signature: <i>Chih-Tien Chang</i>	Date: <i>Jan. 04, 2010</i>
Residence: Hsinchu Hsien	
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Full Name of Joint Inventor: Ju-Ming Chou	
Inventor's Signature: <i>Ju-Ming Chou</i>	Date: <i>Jan. 04, 2010</i>
Residence: Hsinchu Hsien	
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